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(71)Applicant : FUJITSU LTD

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(54) POLYMER COMPLEX AND ITS PRODUCTION

(57)Abstract:

PURPOSE: To obtain a polymer complex excellent in low stress and having a new sea-island structure and to supply a low stress insulation film using the complex.

CONSTITUTION: This polymer complex of a sea-island structure especially, the insulating film comprises a polyimide resin consisting essentially of a tetracarboxylic acid dianhydride, an aromatic and a curable resin. A solvent is removed from a mixed solution of a polyamic acid and an uncured curable resin (acrylic or phosphazene-based curable resin) under a proper condition to give a sea-island structure. The curable resin is cured by light exposure, etc., optionally developed and then the polyamic acid is subjected to ring closure through dehydration.

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(21)Application number : 2000-006656

(71)Applicant : MITSUBISHI GAS CHEM CO INC

(22)Date of filing : 14.01.2000

(72)Inventor : YAMADA TOSHIAKI
BAN HAJIME
IKEDA HIBIKI

(54) THERMOSETTING RESIN COMPOSITION

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a thermosetting resin composition having a low dielectric constant.

SOLUTION: This thermosetting resin composition is prepared by compounding (1) 100 pts.wt. of a polyfunctional cyanic ester compound or its prepolymer with both of (2) 0.1-1,000 pts.wt. of a polyimide having an imide ring closure rate of 95-100 mol% and (3) 0.005-5 pts.wt. of a heat curing catalyst as essential components.

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